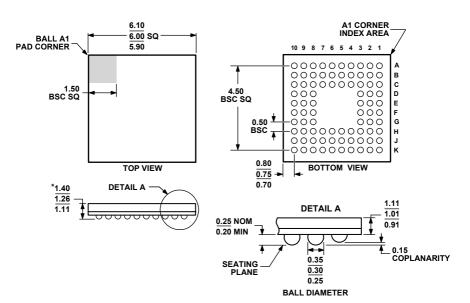


## 84-Ball Chip Scale Package Ball Grid Array [CSP\_BGA] (BC-84-1) Dimensions shown in millimeters



\*COMPLIANT WITH JEDEC STANDARDS MO-195-BC WITH THE EXCEPTION TO PACKAGE HEIGHT.

## Analog Devices BC-84-1 RFVA 6.0 \_\_\_\_\_\_ 4.50 0.40 dia\_

(Dim. are in MM)
LAST MODIFIED 08/30/07